



Product Change Notification - LIAL-25IXJB026

Date:

29 Jul 2019

Product Category:

Ethernet Switches

Affected CPNs:**Notification subject:**

CCB 3287, 3287.001 Final Notice: Qualification of ASE as a new assembly site for selected products of the 0.18um wafer technology available in 64L (10x10x1.4mm) and 48L LQFP (7x7x1.4 mm) packages.

Notification text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and)

Description of Change:

Qualification of ASE as a new assembly site for selected products of the 0.18um wafer technology available in 64L (10x10x1.4mm) and 48L LQFP (7x7x1.4 mm) packages.

Pre Change:

Assembled at TICIP assembly site using EN4900 die attach material and CEL-9200 mold compound material.

Post Change:

Assembled at using CRM-1076WA die attach material and EME-G631H mold compound material.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Taiwan IC Packing Corp. TICIP)	ASE Inc. ASE)
Wire material	Au	Au
Die attach material	EN4900	CRM-1076WA
Molding compound material	CEL-9200	EME-G631H
Lead frame material	C7025	C7025

Impacts to Data Sheet:

None

Change Impact

None

Reason for Change:

To improve by qualifying ASE as

Change Implementation Status:

In Progress

Estimated First Ship Date:

February 04, 2019 (date code: 1906)

NOTE: Please be advised that after the estimated first ship may receive pre and post change parts.

Time Table Summary:

	March 2018	-->	January 2019	February 2019
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Workweek	09	10	11	12	13		01	02	03	04	05	06	07	08	09
Initial PCN Issue Date	X														
Report Availability							X								
Final PCN Issue Date							X								
Estimated Implementation Date												X			

Method to Identify Change:

code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report

Revision History:

March 1, 2018: Issued initial notification.

March 21, 2018: Revised this initial notification to be issued to all affected customers.

March 28, 2018: initial notification to update the subject with reference to CCB 3287.001.

January 04, 2019: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided on February 04, 2019.

January 23, 2019: final notification to correct the device description in the qualification report.

June 17, 2019: final notification to update the MSL Level in the Qualification Report and removed EOL CPN in the Affected Parts List.

July 29, 2019: final notification to update and correct the qualification report for KSZ8873MLL device. The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN LIAL-25IXJB026 Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

KSZ8873MML
KSZ8873MMLI
KSZ8873RLL
KSZ8873RLLI
KSZ8873RLLI-TR
SPNZ801077
KSZ8863FLL
KSZ8863FLLI
KSZ8863FLLI-TR
KSZ8863FLL-TR
KSZ8863MLL
KSZ8863MLLI
KSZ8863MLLI-TR
KSZ8863RLL
KSZ8863RLLI
KSZ8863RLLI-TR
KSZ8873FLL
KSZ8873FLLI
KSZ8873MLL
KSZ8873MLLI
KSZ8873MLLJ